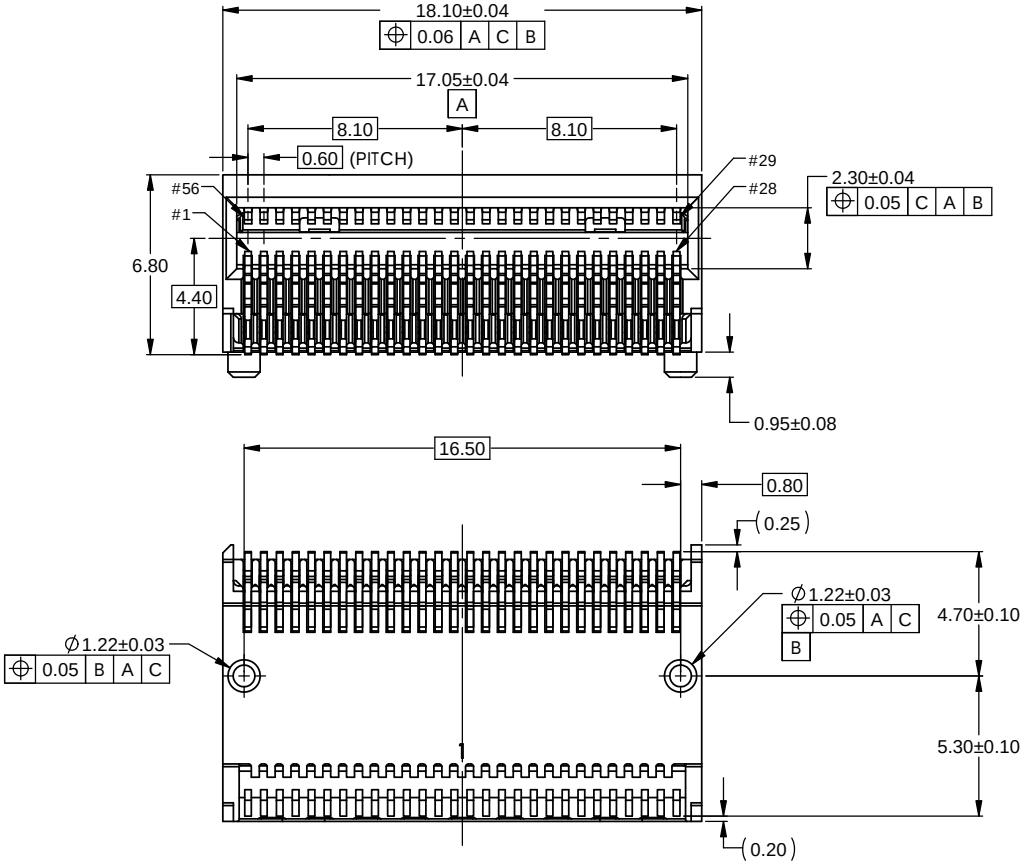
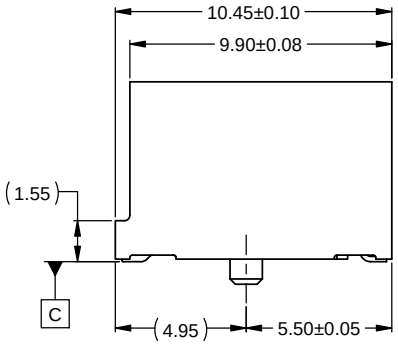
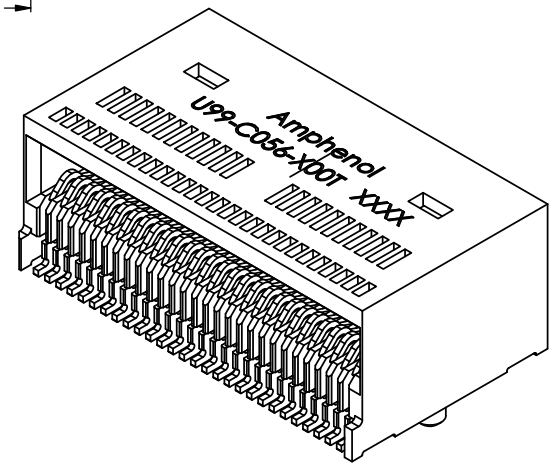
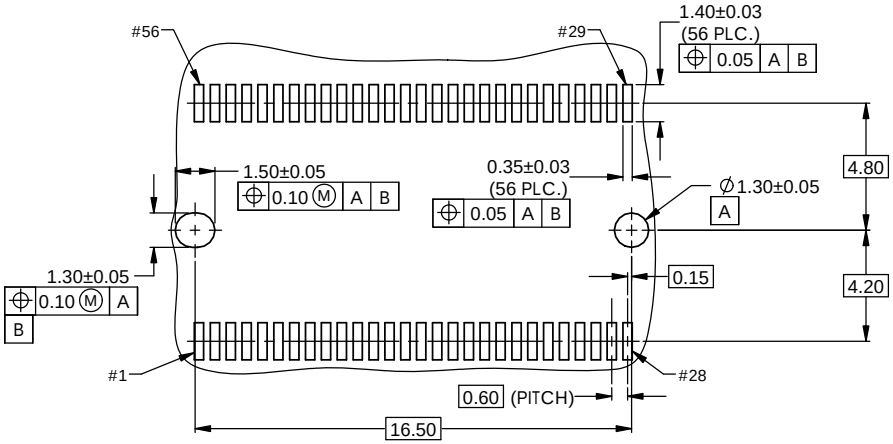
REVISIONS				
REV.	ECN	DESCRIPTION	DATE	APPROVED
A		PROPOSAL	MAY 16/13	CM
B		UPDATED MSA MODIFICATIONS	JUL 30/13	CM
C		DESIGN MODIFICATIONS	JUL 30/14	CM









RECOMMENDED PCB LAYOUT

U99 - C056 - X X X X

OPTIONS

00T = STANDARD CONSTRUCTION WITH TAPE & REEL PACKAGING

CONTACT PLATING OPTION

2 = 30 MICRO INCHES MINIMUM OF GOLD ON MATING END WITH 100 MICRO INCHES MINIMUM OF MATTE TIN ON SOLDER TERMINATION, 50 TO 75 MICRO INCHES OF NICKEL UNDER PLATE ALL OVER

3 = 15 MICRO INCHES MINIMUM OF GOLD ON MATING END WITH 100 MICRO INCHES MINIMUM OF MATTE TIN ON SOLDER TERMINATION, 50 TO 75 MICRO INCHES OF NICKEL UNDER PLATE ALL OVER

NOTES:

1) MATERIAL:

HOUSING: SOLDER REFLOW PROCESS COMPATIBLE LCP, UL94V-0
CONTACTS: PHOSPHOR BRONZE
RESONANCE DAMPENING FEATURE: CONDUCTIVE POLYMER

2) ROHS COMPLIANT

AMPHENOL CANADA CORP. RoHS COMPLIANT 2011/65/EU RECAST

DO NOT SCALE DRAWING

THIS DOCUMENT CONTAINS PROPRIETARY INFORMATION AND SUCH INFORMATION MAY NOT BE DISCLOSED TO OTHERS FOR ANY PURPOSE OR USED FOR MANUFACTURING PURPOSES WITHOUT PERMISSION FROM AMPHENOL CANADA CORP.

	APPROVALS	DATE	
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILIMETERS TOLERANCES ARE: DECIMALS .X± 0.2 .XX± 0.10 ANGLES ± 2°	DRAWN W.JUNG	MAY14/13	Amphenol High Speed Interconnects
	DESIGNED		TITLE CFP4 56 POSITION CONNECTOR
MATERIAL AND FINISH	CHECKED C.MICHLIK	MAY16/13	
	QA APP'D		
ENG.REL.NO.	IE APP'D		SIZE C DWG. NO. P-U99-C056-XXXX REV. C
CODE IDENT. NO. 03554	DWG APP'D C.MICHLIK	MAY16/13	SCALE NTS PROJECT CFP4 SHEET 1 OF 1